

INTERNATIONAL STANDARD



**Semiconductor devices – Micro-electromechanical devices –
Part 30: Measurement methods of electro-mechanical conversion characteristics
of MEMS piezoelectric thin film**

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CONTENTS

FOREWORD.....	4
1 Scope	6
2 Normative references	6
3 Terms and definitions	6
4 Test bed of MEMS piezoelectric thin film	6
4.1 General.....	6
4.2 Functional blocks and components	8
4.2.1 General	8
4.2.2 Clamp.....	8
4.2.3 Linear actuator	8
4.2.4 Displacement meter	9
4.2.5 Electric measurement instrument.....	9
4.2.6 Power source	9
5 Thin film under testing	9
5.1 General.....	9
5.2 Measurement principle	9
5.3 Measuring procedures of direct transverse piezoelectric coefficient	10
5.4 Measuring procedures of converse transverse piezoelectric coefficient.....	10
6 Test report.....	11
Annex A (informative) Example of measuring method of MEMS piezoelectric thin film.....	13
A.1 General.....	13
A.2 Sample preparation procedures	13
A.3 Measuring procedures	13
A.3.1 Measuring procedures of direct transverse piezoelectric coefficient	13
A.3.2 Measuring procedures of converse transverse piezoelectric coefficient.....	15
A.4 Test report	18
A.5 Equation of neutral plane	19
Bibliography.....	20
Figure 1 – Test bed of direct and converse transverse piezoelectric coefficient of MEMS piezoelectric thin film	7
Figure A.1 – Tip displacement and calculated direct transverse piezoelectric coefficient.....	15
Figure A.2 – Input voltage and calculated converse transverse piezoelectric coefficient.....	17
Table 1 – Symbols and designations of test bed	8
Table A.1 – Poling treatment conditions	14
Table A.2 – Material properties for calculation of direct transverse piezoelectric coefficient	14
Table A.3 – Output voltage and calculated transverse piezoelectric coefficient	14
Table A.4 – Material properties for calculation of converse transverse piezoelectric coefficient	16
Table A.5 – Tip displacement of cantilever and calculated transverse piezoelectric coefficient	16

Table A.6 – Example of measuring conditions and results of electro-mechanical characteristics of piezoelectric thin film as mandatory	18
Table A.7 – Example of measuring conditions and results of electro-mechanical characteristics of piezoelectric thin film as optional	19

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MICRO-ELECTROMECHANICAL DEVICES –****Part 30: Measurement methods of electro-mechanical conversion
characteristics of MEMS piezoelectric thin film**

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SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 30: Measurement methods of electro-mechanical conversion characteristics of MEMS piezoelectric thin film

1 Scope

This part of IEC 62047 specifies measuring methods of electro-mechanical conversion characteristics of piezoelectric thin film used for micro sensors and micro actuators, and its reporting schema to determine the characteristic parameters for consumer, industry or any other applications of piezoelectric devices. This document applies to piezoelectric thin films fabricated by MEMS process.

2 Normative references

There are no normative references in this document.